



NPN Transistor Bare Die - BC548

Rev 1.0
08/01/19

General purpose medium power amplifier or switch in bare die form
Complement to PNP BC558

Features:

- Gain graded
- Low saturation voltage
- Well suited for amplifier applications
- High reliability gold back metal
- High reliability tested grades for Military + Space

Ordering Information:

The following part suffixes apply:

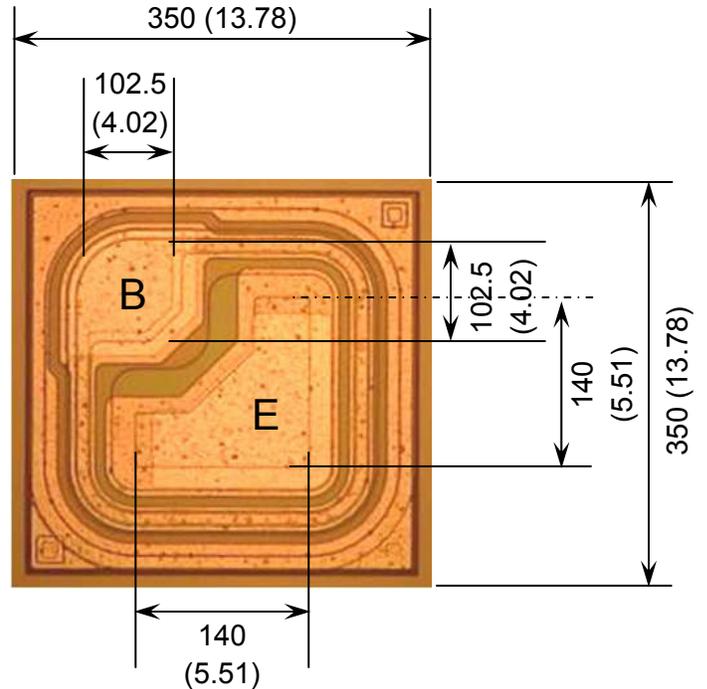
- No suffix - MIL-STD-750 /2072 Visual Inspection
- "H" - MIL-STD-750 /2072 Visual Inspection + MIL-STD-38534 Class H LAT
- "K" - MIL-STD-750 /2072 Visual Inspection + MIL-STD-38534 Class K LAT

LAT = Lot Acceptance Test.

For further information on LAT process flows see below.

www.siliconsupplies.com/quality/bare-die-lot-qualification

Die Dimensions in μm (mils)



E = EMITTER **B** = BASE

DIE BACK = COLLECTOR

Supply Formats:

- Default – Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape – Specific request
- Unsawn Wafer – Specific request
- With additional electrical selection – Specific request
- Sawn as pairs or adjacent pair pick – Specific request

Mechanical Specification

Die Size (Excluding Saw Street)	350 x 350 13.78 x 13.78	μm mils
Base Pad Size	102.5 x 102.5 4.02 x 4.02	μm mils
Emitter Pad Size	96 x 96 5.51 x 5.51	μm mils
Die Thickness	230 (± 15) 9.06 (± 0.59)	μm mils
Top Metal Composition	Al - 1.3 μm	
Back Metal Composition	AuAs - 0.9 μm	





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Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise stated

PARAMETER	SYMBOL	VALUE	UNIT
Collector-Base Voltage	V_{CB0}	30	V
Collector-Emitter Voltage	V_{CEO}	30	V
Emitter-Base Voltage	V_{EBO}	5	V
Collector Current	I_C	100	mA
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to 150	$^\circ\text{C}$

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT		
OFF CHARACTERISTICS								
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	$I_C = 50\mu\text{A}, I_E = 0$	50	-	-	V		
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	$I_C = 1\text{mA}, I_B = 0$	45	-	-	V		
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	$I_E = 50\mu\text{A}, I_C = 0$	6	-	-	V		
Collector Cut-off Current	I_{CBO}	$V_{CB} = 30\text{V}, I_E = 0$	-	-	15	nA		
ON CHARACTERISTICS								
Forward-Current Transfer Ratio	h_{FE}	BC548	$V_{CE} = 5\text{V}, I_C = 2\text{mA}$	110	-	800	-	
		BC548A		110	-	220	-	
		BC548B		200	290	450	-	
		BC548C		420	-	800	-	
	h_{FE}	BC548B	$V_{CE} = 5\text{V}, I_C = 10\mu\text{A}$	-	150	-	-	
		BC548C		-	270	-	-	
		BC548A		$V_{CE} = 5\text{V}, I_C = 100\text{mA}$	-	120	-	-
		BC548B			-	180	-	-
BC548C	-	300	-		-			
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 10\text{mA}, I_B = 0.5\text{mA}$	-		90	250	mV	
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C = 10\text{mA}, I_B = 0.5\text{mA}$	-	700	-	mV		
		$I_C = 100\text{mA}, I_B = 5\text{mA}$	-	900	-	mV		
Base-Emitter On Voltage	$V_{BE(on)}$	$I_C = 2\text{mA}, V_{CE} = 5\text{V}$	580	660	700	mV		
		$I_C = 10\text{mA}, V_{CE} = 5\text{V}$	-	-	720	mV		
SMALL SIGNAL CHARACTERISTICS¹								
Transition Frequency	f_T	$V_{CE} = 5\text{V}, I_C = 10\text{mA}, f = 100\text{MHz}$	150	300	-	MHz		
Small-Signal Current Gain	h_{fe}	BC548	$V_{CE} = 5\text{V}, I_C = 2\text{mA}, f = 1\text{kHz}$	125	-	900		
		BC548B		240	330	500		
		BC548C		450	600	900		
Output Capacitance	C_{obo}	$V_{CB} = 10\text{V}, I_E = 0, f = 1\text{MHz}$	-	3.5	6	pF		
Input Capacitance	C_{ibo}	$V_{BE} = 10\text{V}, I_C = 0, f = 1\text{MHz}$	-	9	-	pF		
Noise Figure	NF	$V_{CE} = 5\text{V}, I_C = 200\mu\text{A}, f = 1\text{KHz}, R_G = 2\text{K}\Omega$	-	2	10	dB		

Note 1: Not production testing in die form. Characterized by chip design and tested in package





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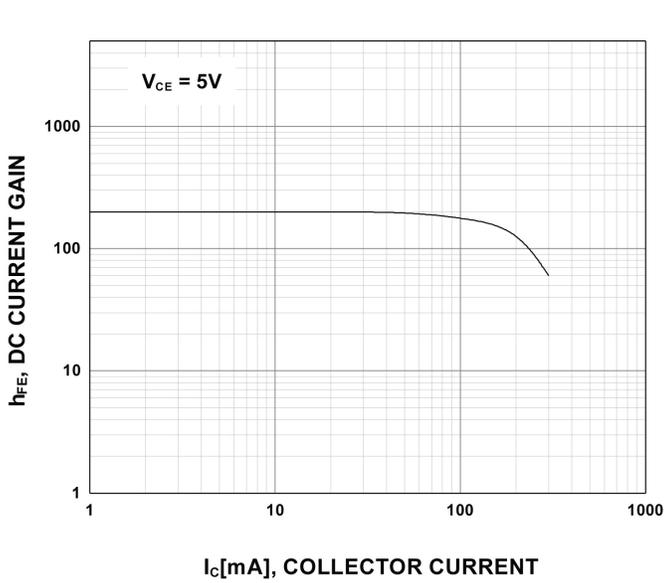


Figure 1 – DC Current Gain

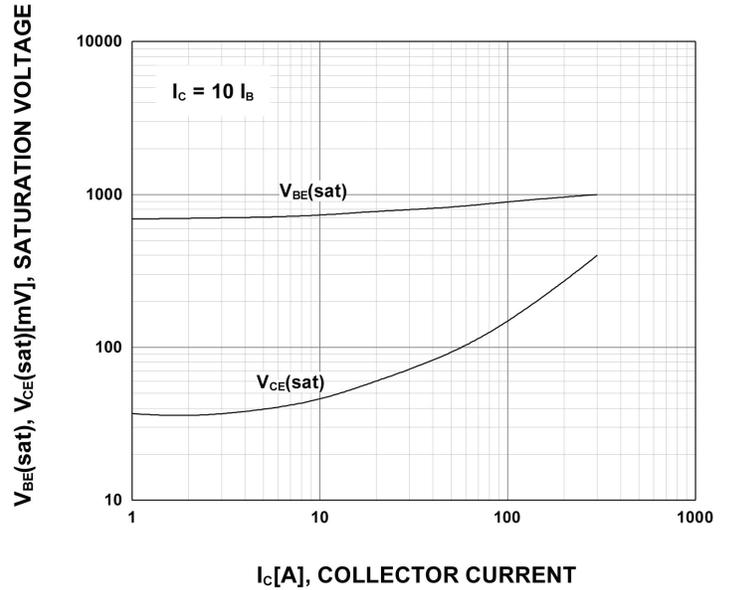


Figure 3 – Base-Emmitter Saturation Voltage versus Collector-Emmitter Saturation Voltage

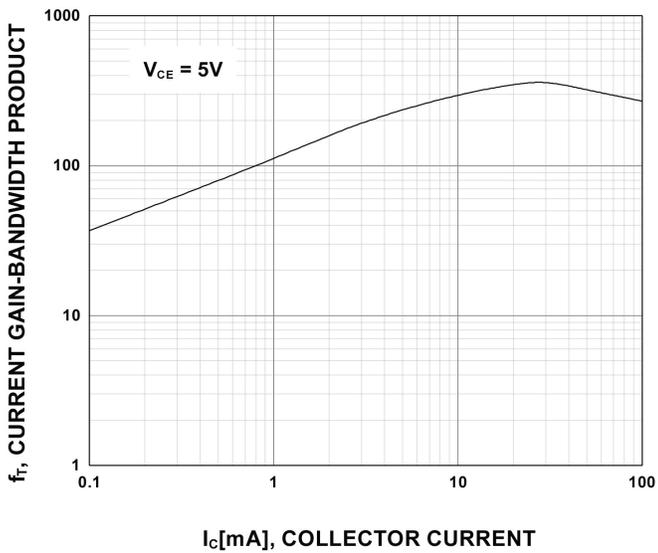


Figure 3 – Current Gain Bandwidth Product

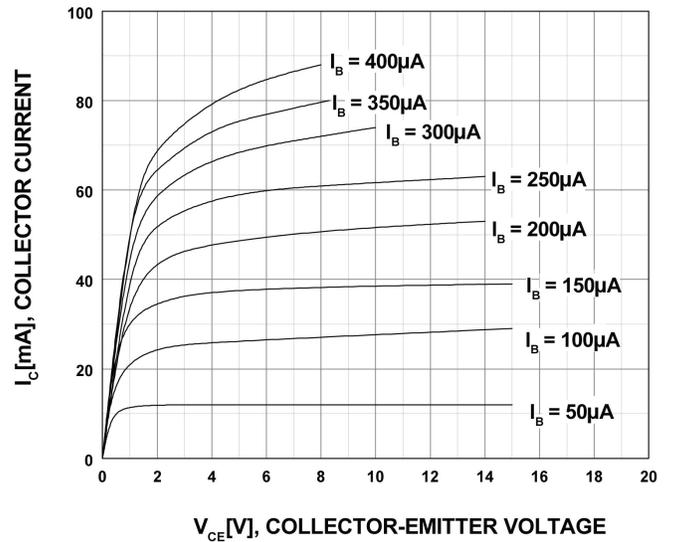


Figure 4 – Static Characteristics





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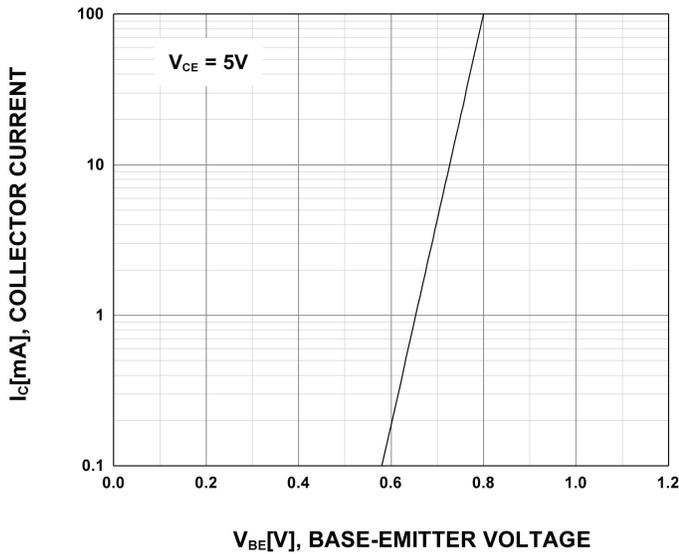


Figure 5 – Transfer Characteristic

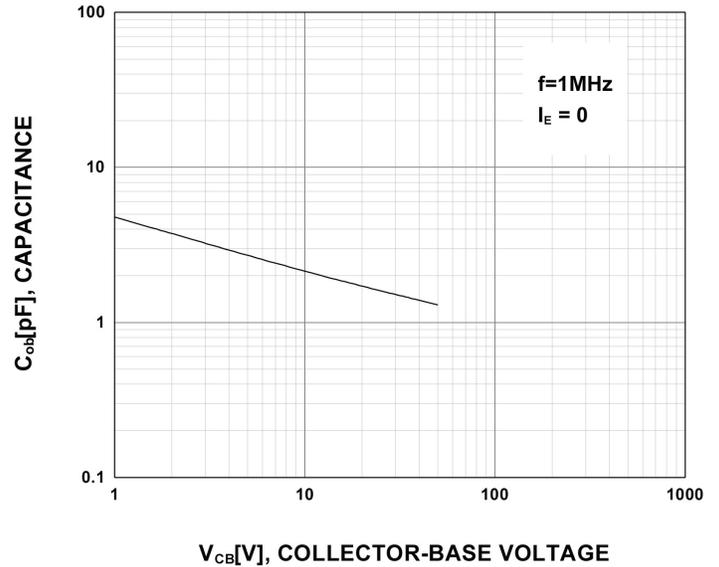


Figure 6 – Output Capacitance

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